

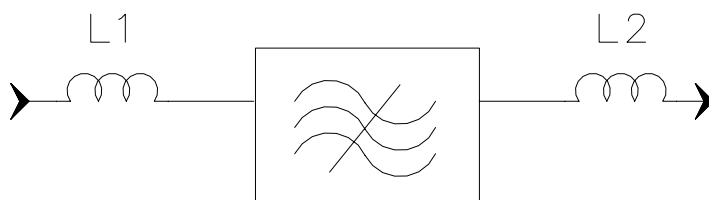
Specifications

| Parameter | Unit | Minimum | Typical | Maximum |
|---------------------|------|---|---------|---------|
| Center Frequency | MHz | 75.59 | 75.64 | 75.69 |
| Insertion Loss | dB | | 22 | 25 |
| 3 dB Bandwidth | MHz | 1.5 | 1.59 | |
| 40 dB Bandwidth | MHz | | 2.56 | 2.7 |
| Passband Variation | dB | | 0.6 | 1 |
| Absolute Delay | usec | | 2.61 | |
| Ultimate Rejection | dB | 48 | 50 | |
| Substrate Material | | | quartz | |
| Ambient Temperature | °C | | 25 | |
| Package Size | | DIP2212 (22.2x12.8x4.7mm ³) | | |

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show


Matching Configuration



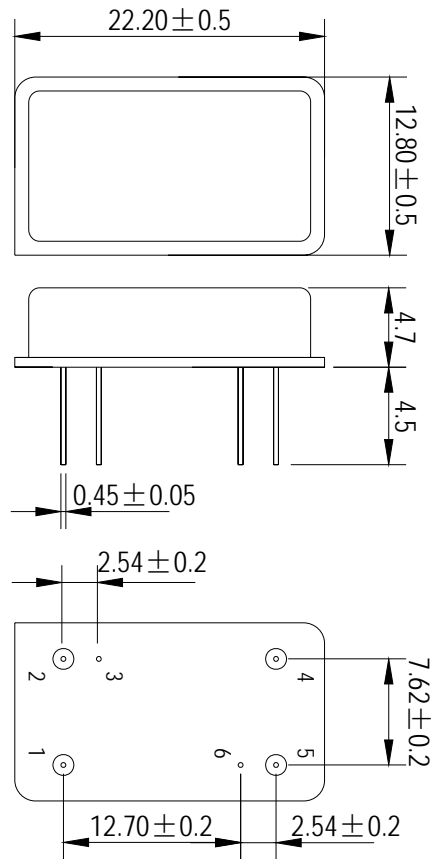
L1=L2=220nH

Source/Load Impedance=50 ohm

Notes - Component values may change depending on board layout.

| | | | | |
|--|---|-------------|------------|------|
|  | SIPAT Co., Ltd. (CETC No. 26 Research Institute) Nanping Huayuan Road No. 14 Chongqing, China, 400060 | Part Number | LBS07503 | |
| | | Rev. Date | 2004-12-30 | |
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Package Dimension

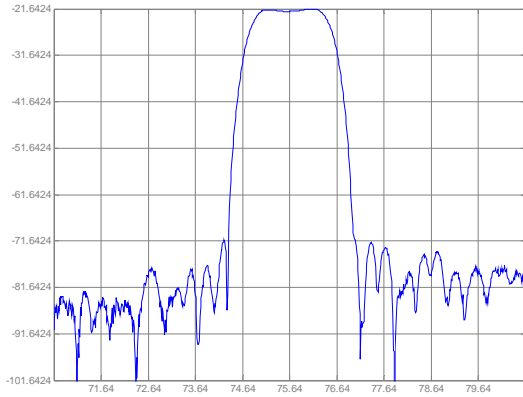


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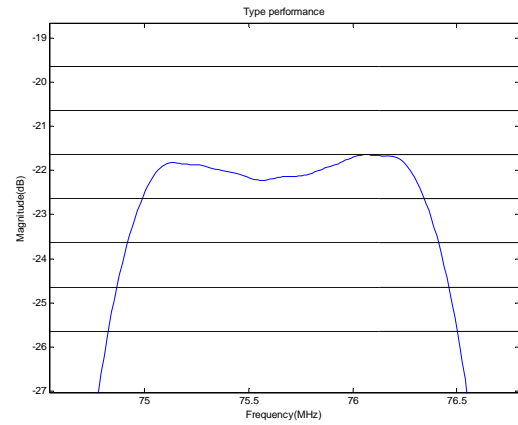
| | | |
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Typical Performance

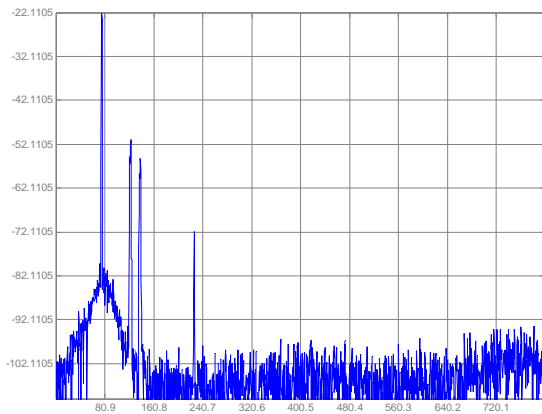
Frequency Respond



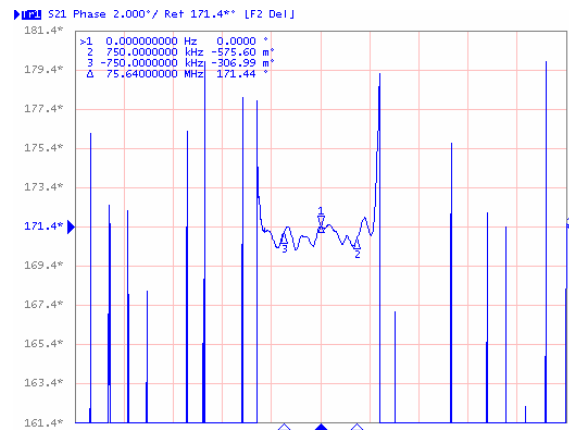
Passband Respond



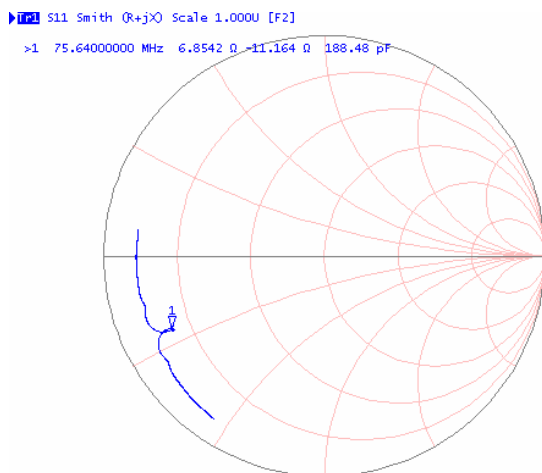
Wideband Respond



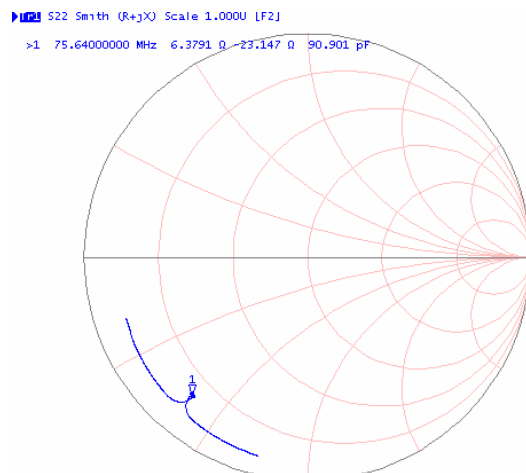
Phase Linearity($f_0 \pm 750\text{KHz}$)



Simth Chart S11



Simth Chart S22



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